

Six Channel SiC MOSFET Driver

Gate Driver for 1200V SiC MOSFET Power Module

Features

- 6 output channels
- Isolated power supply
- Direct mount low inductance design
- Short circuit protection
- Over temperature protection
- Under voltage protection

For use with Cree Module

- 45mm, six-pack CCS020M12CM2
- 45mm, six-pack CCS050M12CM2

Applications

- Driver for SiC MOSFET modules in two-level, three-phase inverter applications
- DC Bus voltage up to 1000VDC

Absolute Maximum Ratings



Part Number	Package	Marking
CGD15FB45P1	PCBA	CGD15FB45P1

Symbol	Parameter Value		Unit	Test Conditions	Note	
Vs	Power Supply Voltage	16	V	Vs ramp rate >50V/sec		
V _{iH}	Input signal voltage HIGH	5	V			
V _{iL}	Input signal voltage LOW	0	V			
I _{O.pk}	Output peak current	±9 (±2)	А	Rg limited		
P _{O_AVG}	Ouput power per gate	1.2	W			
F _{Max}	Max. Switching frequency	250	kHz	Vg=+20/-5, Rg=10Ω		
V _{DS}	Max. Drain to source voltage	1200	V			
V _{isol}	Input to output isolation voltage	±1200	V			
dv/dt	Rate of change of output to input voltage	50,000	V/µs			
W	Weight	223	g			
MTBF	Mean time between failure	1.5	10 ⁶ h			
T _{op}	Operating temperature	-35 to 85	°C			
T _{stg}	Storage temperature	-40 to 85	°C			



Characteristics

Symbol	Parameter	Min	Value Typ	Мах	Unit	Test Conditions	Notes
Vs	Supply voltage	14	15.0	16	V		
Vi	Input signal voltage on/off		5/0		V		
•	Supply current (no load)		230		-	25C	
I _{SO}	Supply current (max.)		460		mA	f=100khz, 25C	
00	Supply current (max.)		780			f=250khz, 25C	
V _{iT+}	Input threshold voltage HIGH	3.5			V		
V _{iT-}	Input threshold voltage LOW			1.5	V		
R _{in}	Input resistance		48		kΩ		
Cio	Coupling capacitance		30		pf		
T _{don}	Turn on propogation delay		300		nS	Time from when input pin goes high until driver output goes high	Fig. 3, 4
T _{doff}	Turn off propogation delay		300		nS	Time from when input pin goes low until driver output goes low	Fig. 3, 4
T _{Rout}	Output voltage rise time		65		nS	V_{OUT} time from 10% to 90% with R_G = 0ohms, C_{LOAD} = 40,000pf	Fig. 5
T _{Fout}	Output voltage fall time		50		nS	V_{OUT} time from 90% to 10% with R_G = 0ohms, C_{LOAD} = 40,000pf	Fig. 5
R _{GON}	Turn-on gate resistor		10		Ω		
R _{GOFF}	Turn-off gate resistor		10		Ω		
V _{GATEON}	Gate voltage at turn-on		+20		V		
V _{GATEOFF}	Gate voltage at turn-off		-5		V		
T _{SC}	Short Circuit Response Time		2.34		μS	Total time from when short circuit current begins flowing until it is interrupted	
V _{DS,TRIP}	V _{DS} monitoring threshold		4.7		V	V _{DS} value that causes the driver to trip on overcurrent	
T _{FLT_DLY}	Fault Delay Time		425		nS	Time from when desat pin=9V until the gate output begins turning off	
T _{FLT_SIG}	Transmission delay of fault state			2.25	μS	Time delay from desat pin=9V until fault status pin is pulled low	
T _{err}	Pulse width for resetting fault	800			nS	Time reset pin must be held low to reset driver	
	Test voltage (60Hz/1min), Primary to secondary		4000		V		
	Test voltage (60Hz/1min), Secondary to secondary		4000		V		
	Creepage distance, Primary to secondary		9.0		mm		
	Creepage distance, Secondary to secondary		7.0		mm		
	Clearance distance, Primary to secondary		6.0		mm		
	Clearance distance, Secondary to secondary		7.0		mm		









Note: Default gate resistor for Rg is 10Ω for gate ON and OFF. The user can control the gate turn ON and OFF speed by changing Rg to a lower value and gain better MOSFET switching efficiency. The user can also control the Gate turn-ON and OFF speed independently by populating Rg.off and D1. Cs is made up of 3x 2.2nF, 1.2kV film capacitors.

3



X1 – Signal interface

1	PWM_Upper_A (5V Logic)	2	
3	PWM_Lower_A (5V Logic)	4	
5	PWM_Upper_B (5V Logic)	6	
7	PWM_Lower_B (5V Logic)	8	
9	PWM_Upper_C (5V Logic)	10	
11	PWM_Lower_C (5V Logic)	12	
13	/RST (normally hi)	14	COMMON
15	RDY (normally hi)	16	
17	DESAT FAULT (normally low)	18	
19	OVER_TEMP_FLT (normally low)	20	
21		22	
23	PWR In (Vs)	24]
25		26	

	LED Status Indicators					
LED Sta						
L1	RED led, illuminated when Phase A upper switch has a desat fault.	L2	RED led, illuminated when Phase A lower switch has a desat fault.			
L3	RED led, illuminated when Phase B upper switch has a desat fault.	L4	RED led, illuminated when Phase B lower switch has a desat fault.			
L5	RED led, illuminated when Phase C upper switch has a desat fault.	L6 RED led, illuminated wher Phase C lower switch has desat fault.				
L7	GREEN led, illuminated when power is present and all faults are clear.	L8	RED led, illuminated when there is an over temp fault.			







Turn-off propogation delay











Figure 5. Output Voltage Rise and Fall Times

Fault Handling

Each of the six gate drive channels is protected by a desaturation (desat) circuit. In the event of a short circuit, the voltage across the MOSFET (V_{DS}) rises until it hits a threshold which causes the desat circuit to drive all six gate drive channels to their off state. Pin 17 of the X1 signal connector toggles high when a desat event occurs. There will also be a red LED (L1-L6) illuminated for the gate drive channel(s) that activated the desaturation protection. Once the fault is cleared, the circuit can be reset with the onboard reset button or remotely by driving pin 13 of the X1 connector to common.

There is an overtemperature protection circuit that turns off all the gates in the event an overtemperature is detected. The overtemperature circuit reads the value of the six pack module's onboard temperature sensor. When the sensor reaches a value corresponding to 115°C, the overtemperature circuit is activated and all six gate drive channels are driven to their low state. Pin 19 of the X1 connector is toggled high when an overtemperature fault occurs.

CPU Vs, PWM, /RST OVER TMP. DESAT and /RDY X1 Connector GCD 15FB45P - 6-ch, SiC Gate Driver Isolation DCpos ш DCneg Out Out Out Module Interface ₹ 12 4 13,14 27.28 Cree 45mm, 1.2kV, SiC MOSFET 6-pak Module

Typical Application

5



Mechanical Instructions

Designed to directly mount to Cree 45 mm style power modules, the 6-ch gate driver also has several other mounting holes to secure the assembly.

Attach the gate driver board to the power module via the 4x Module screw holes (see diagram below) using the recommended hardware in Table 1. Then solder the 28x solder pins via the solder pin holes to electrically connect the driver board to the power module. The soldering tip must not exceed 260°C and contact with the solder per pin must not exceed 10 seconds. The solder joints should be in accordance with IPC A 610 Rev D (or later) – Class 3 to ensure an optimal connection between the module and gate driver board.

The module plus driver board assembly must be further supported by securing the assembly to standoffs via the 7x Mounting holes shown in the figure below.



Table 1 Hardware List

Ref	Description	Hardware	Locations	Torque
Module screw holes	2.5mm clearance holes for mounting screws to secure the module to the printed circuit board assembly.	M2.5 x 4mm	4x	0.5 Nm
Mounting holes	4.3mm clearance holes for screws to secure the circuit assembly to stand-offs for additional support.	6-32 x 5/6" Zinc Plated pan head screw /w internal tooth washer.	9x	0.9 Nm
Access holes	10mm clearance hole to provide access to the screw that secure the module to the heatsink.	n/a	2x	n/a
Solder pin holes	1.6mm plated holes for solder pins from power module.	Solder pins from power module	28x	n/a
Power terminals	6mm holes to secure power cables.	¼" or 6mm hardware	7x	

6



Mechanical Drawing (units in Inches) [mm]





This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems or air traffic control systems.

Cree, Inc. 4600 Silicon Drive Durham, NC 27703 USA Tel: +1.919.313.5300 Fax: +1.919.313.5451 www.cree.com/power

Copyright © 2015 Cree, Inc. All rights reserved. The information in this document is subject to change without notice. Cree and the Cree logo are registered trademarks and Z-REC and Z-FET are trademarks of Cree, Inc.



Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;

- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);

- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;

- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком):

- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибьютором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «JONHON», а так же официальным дистрибьютором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «FORSTAR».



«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«FORSTAR» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



Телефон: 8 (812) 309-75-97 (многоканальный) Факс: 8 (812) 320-03-32 Электронная почта: ocean@oceanchips.ru Web: http://oceanchips.ru/ Адрес: 198099, г. Санкт-Петербург, ул. Калинина, д. 2, корп. 4, лит. А